### Material Composition

**Part Number:** 1N5711WS-(p)-F  
**Weight (mg):** 5.2603

#### Element Material Group  |  Material  | CAS (if applicable)  | Average mass homogeneous Material(%)  | Percent of whole (%)  | Mass (mg) Homogeneous Material  | ppm Homogeneous Material  | ppm overall  
--- | --- | --- | --- | --- | --- | --- | ---  
**Chip**  | Silicon w/Metal  | Doped Silicon*  |  |  |  |  |  
|  | Fe  | 7439-89-6  | 57.65%  |  | 0.0562  | 1000000  | 10684  
|  | Mn  | 7439-96-5  | 60.00%  |  | 1.2809  | 410000  | 98836  
|  | Co  | 7440-48-4  | 0.50%  |  | 24.35  | 50000  | 1212  
|  | Si  | 7440-21-3  | 0.15%  |  | 1000000  | 9600  | 5500  
|  |  |  | 100.00%  | 1.07  | 0.0505  | 1000000  | 9600  
| **Leadframe**  | Alloy 42  |  |  |  |  |  |  
|  | Fe  | 7439-89-6  | 57.65%  |  | 0.0562  | 1000000  | 10684  
|  | Cr (not Cr 6+)  | 7440-47-3  | 0.10%  |  | 24.35  | 50000  | 1212  
|  | Si  | 7440-21-3  | 0.15%  |  | 1000000  | 9600  | 5500  
|  |  |  | 100.00%  | 1.07  | 0.0505  | 1000000  | 9600  
| **Leadframe Plating**  | Silver  | Plating Silver  |  |  |  |  |  
|  | Fe  | 7439-89-6  | 57.65%  |  | 0.0562  | 1000000  | 10684  
|  | Cr (not Cr 6+)  | 7440-47-3  | 0.10%  |  | 24.35  | 50000  | 1212  
|  | Si  | 7440-21-3  | 0.15%  |  | 1000000  | 9600  | 5500  
|  |  |  | 100.00%  | 1.07  | 0.0505  | 1000000  | 9600  
| **Bond Wire**  | Gold Wire  | Bond Wire Gold  |  |  |  |  |  
|  | Si  | 7440-21-3  | 0.15%  |  | 1000000  | 9600  | 5500  
|  |  |  | 100.00%  | 1.07  | 0.0505  | 1000000  | 9600  
| **Encapsulation**  | KTMC1050G  | Encapsulation KTMC1050G  |  |  |  |  |  
|  | Silicone dioxide  |  | 69.50%  |  | 89.95%  | 89000  | 45974  
|  | Ortho Cresol Novolac Epoxy Resin  | 29980-82-2  | 12.25%  |  | 70.55  | 80000  | 46974  
|  | Basic Durmer Phenolic resin (Compound of polymeric network)  | 9003-35-4  | 5.50%  | 0.14  | 0.0076  | 1000000  | 1440  
|  |  |  | 100.00%  | 70.55  | 3.711  | 182900  | 86420  
|  | Misc. system  |  | 12.75%  |  |  | 127500  | 89948  
|  | Carbon black  |  | 0.50%  |  |  | 50000  | 3527  
|  |  |  | 100.00%  | 2.93  | 0.1541  | 1000000  | 9600  
| **Lead Plating Finish**  | Matte Tin  | Lead Plating Finish Matte Tin  |  |  |  |  |  
|  | Tin  | 7440-31-5  | 100.00%  | 2.93  | 0.1541  | 1000000  | 29295  
|  |  |  | 100.00%  | 5.2603  | 1000000  | 1000000  | 46974  

**Tolerance:** ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness.

* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as currently exempted by ELV II and RoHS and reported above:

- **Asbestos**
- **Azo compounds**
- **Cadmium and cadmium compounds**
- **Certain Shortchain Chlorinated Paraffins**
- **Chlorinated organic compounds**
- **Hexavalent chromium compounds**
- **Lead and lead compounds**
- **Mercury and mercury compounds**
- **Organic tin compounds**
- **Ozone Depleting Substances - Class I (CFCs, HCFCs, etc.)**
- **Ozone Depleting Substances - Class II (HFCs)**
- **Perfluorocontaine Sulphonic (PFOS) or related compounds**
- **Polybrominated diphenyl ethers (PBDE) including DecaBDE**
- **Polychlorinated Biphenyls (PCBs)**
- **Polychlorinated Naphthalenes (> 3 chlorine atoms)**
- **Perfluorooctane Sulphonate (PFOS) or related compounds**
- **Radioactive Substances**
- **Tributyl Tin (TBT) and Triphenyl Tin (TPT)**
- **Tributyl Tin Oxide (TBTO)**

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